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(12) **United States Design Patent** (10) **Patent No.:** **US D892,068 S**  
**Choi et al.** (45) **Date of Patent:** **\*\* \*Aug. 4, 2020**

(54) **LIGHT EMITTING DIODE PACKAGE**

(56) **References Cited**

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Ansan-si (KR)

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(72) Inventors: **SeungRi Choi**, Ansan-si (KR); **SeMin Bang**, Ansan-si (KR); **MyungHee Lee**,  
Ansan-si (KR)

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(\* ) Notice: This patent is subject to a terminal disclaimer.

(\*\*) Term: **15 Years**

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PLC

(30) **Foreign Application Priority Data**

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(52) **U.S. Cl.**  
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(58) **Field of Classification Search**  
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D26/2, 25, 35, 74, 80, 81  
CPC ... H01L 25/167; H01L 25/0753; H01L 27/15;  
H01L 27/156; H01L 31/02; H01L 33/00;  
H01L 33/04; H01L 33/08; H01L 33/10;  
H01L 33/20; H01L 33/38; H01L 33/42;  
H01L 33/48; H01L 33/483; H01L 33/486;  
F21S 43/14; F21S 43/145; F21S 43/15;  
F21S 43/20

See application file for complete search history.

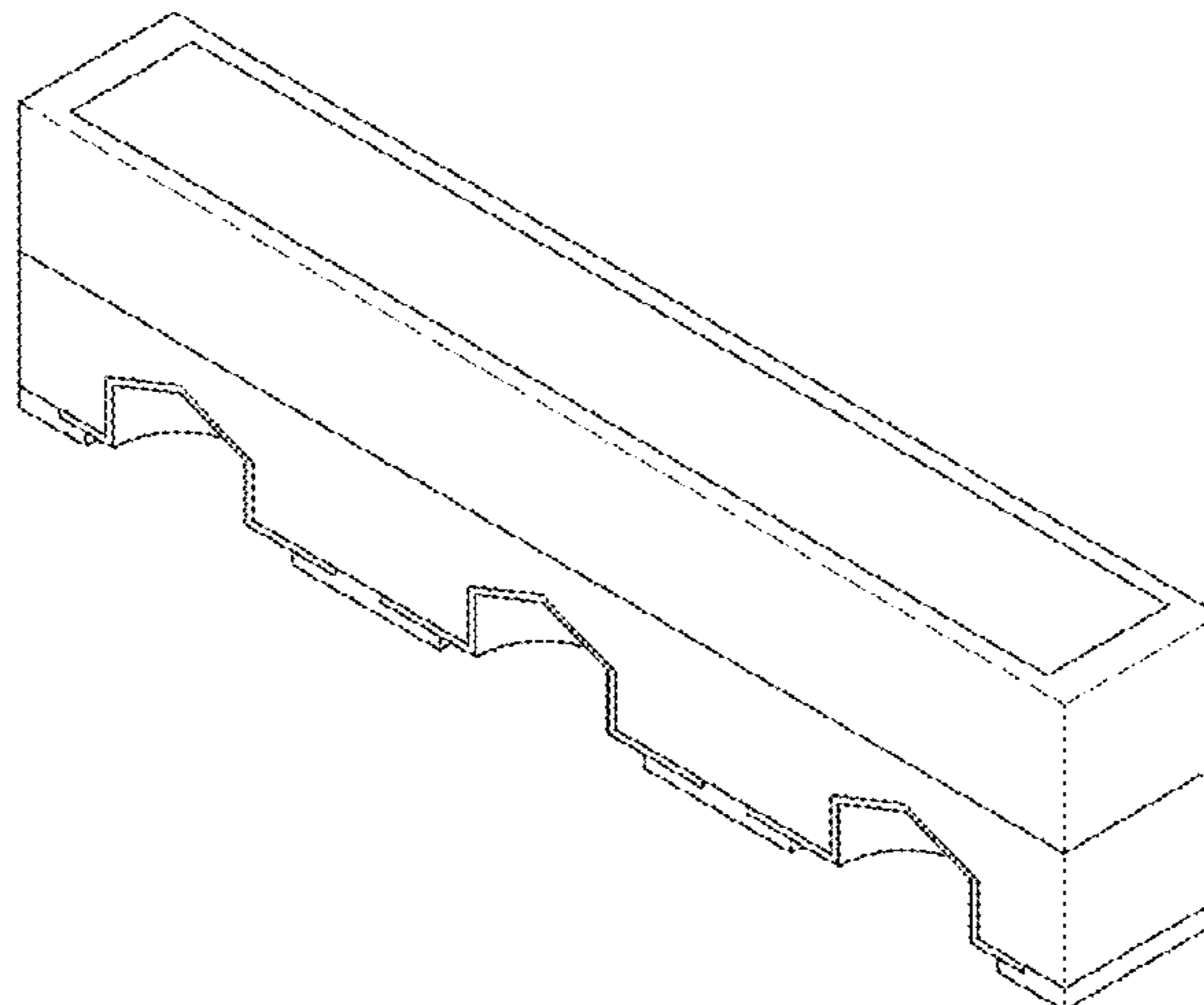
(57) **CLAIM**

The ornamental design for light emitting diode package, as shown and described.

**DESCRIPTION**

- 1. Light emitting diode package
- 1.1 : Perspective
- 1.2 : Front
- 1.3 : Back
- 1.4 : Left
- 1.5 : Right
- 1.6 : Top
- 1.7 : Bottom

**1 Claim, 7 Drawing Sheets**



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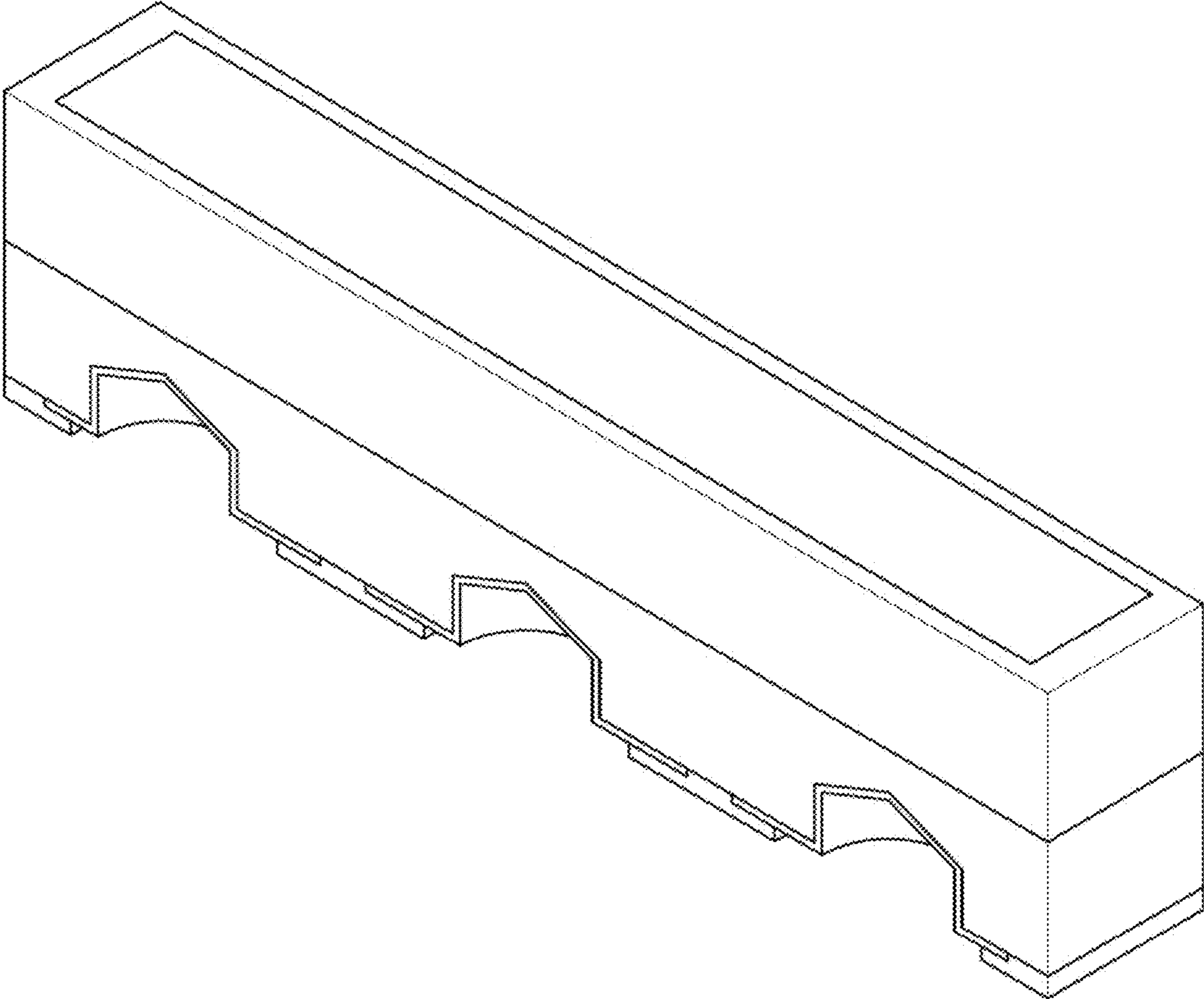
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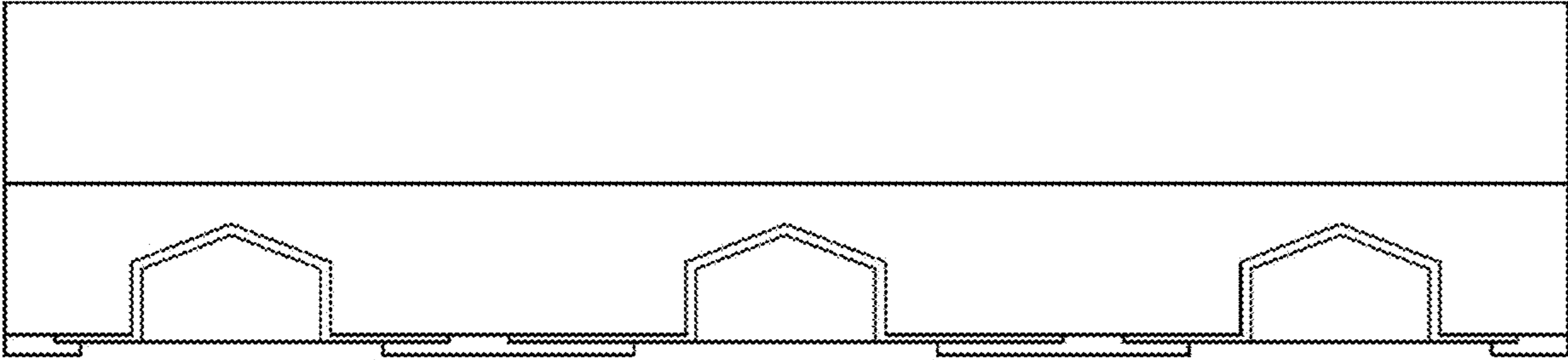
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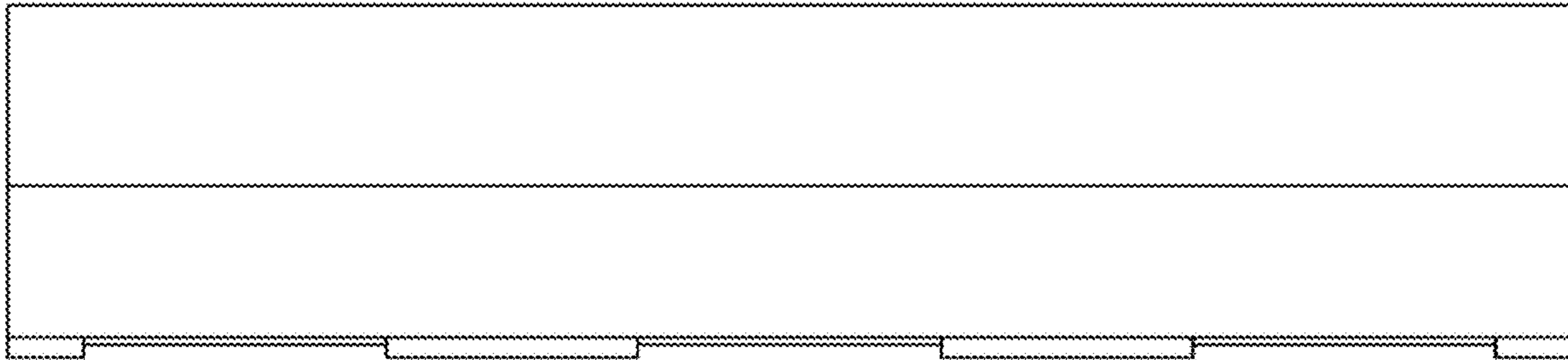
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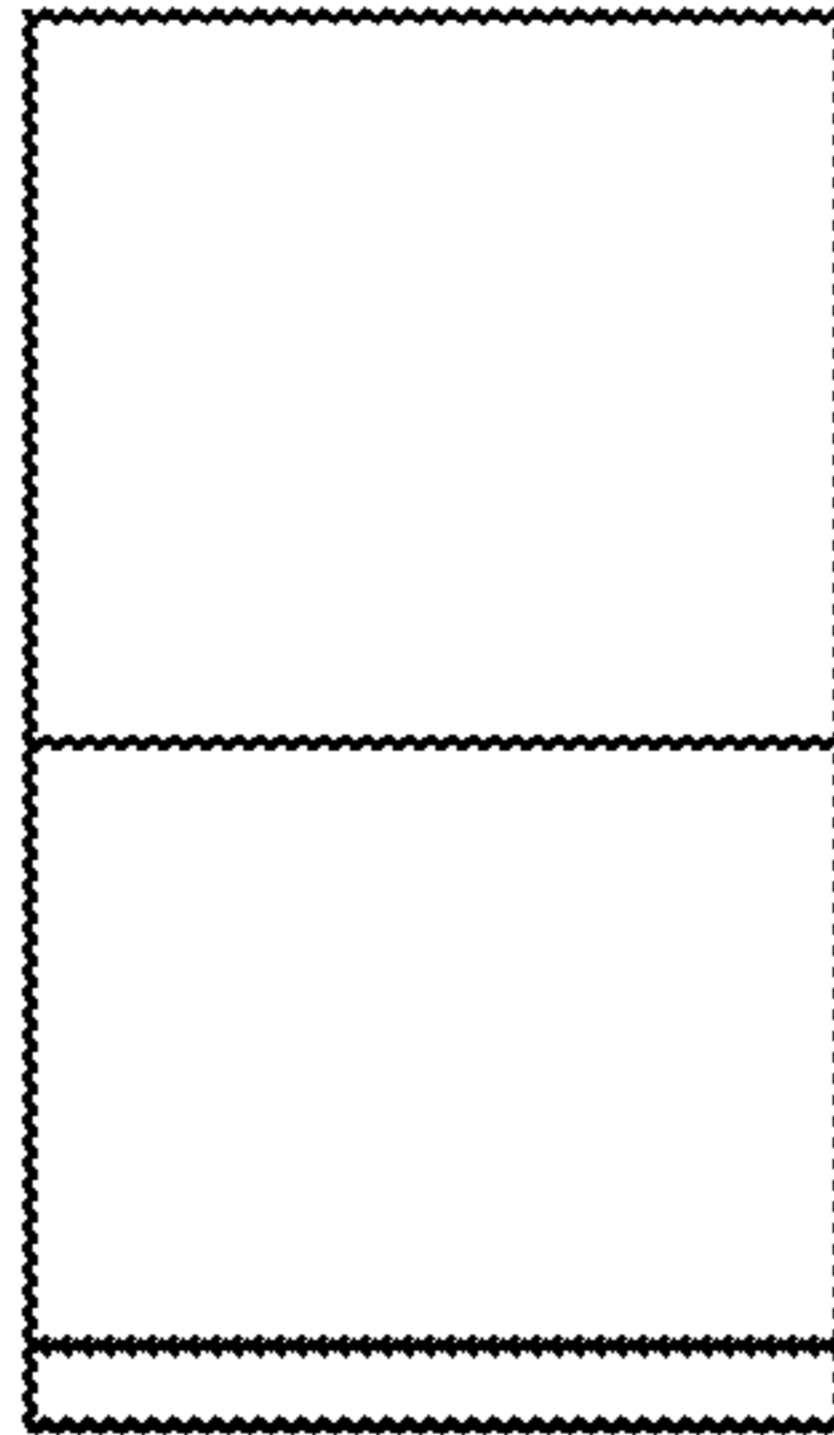
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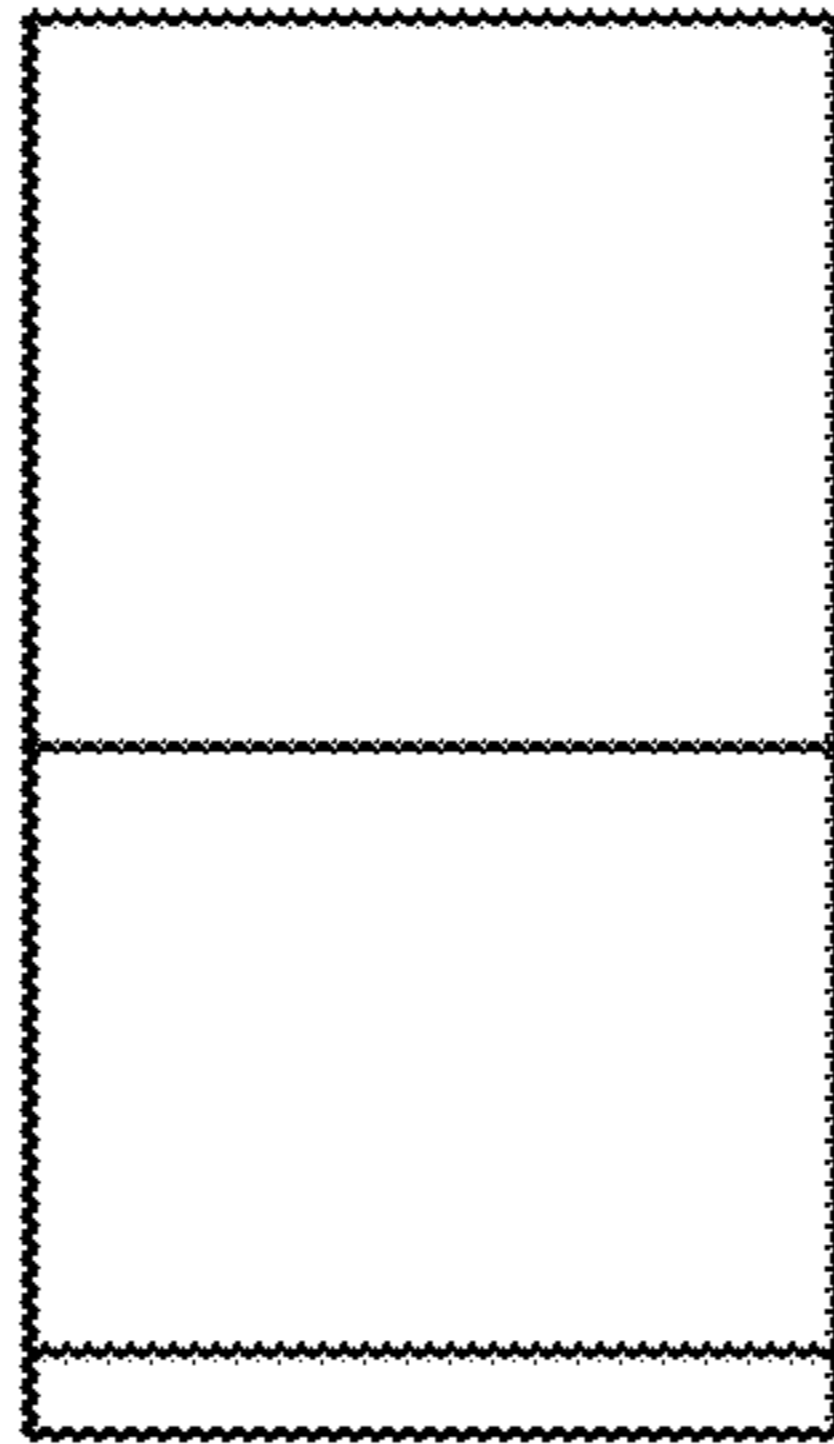
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